### 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- Average forward current:  $I_{F(AV)} \le 2 A$
- Reverse voltage: V<sub>R</sub> ≤ 30 V
- Low forward voltage
- High power capability due to clip-bond technology
- Qualified according to AEC-Q101 and recommended for use in automotive applications
- Small and flat lead SMD plastic package
- · Suitable for both reflow and wave soldering

### 3. Applications

- · Low voltage rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- · Reverse polarity protection
- Low power consumption applications

### 4. Quick reference data

Table 1. Quick reference data

| Symbol             | Parameter               | Conditions   |     | Min | Тур | Max | Unit |
|--------------------|-------------------------|--|-----|-----|-----|-----|------|
| I <sub>F(AV)</sub> | average forward current | $\delta$ = 0.5; f = 20 kHz; square wave; T <sub>amb</sub> ≤ 100 °C     | [1] | -   | -   | 2   | A    |
|                    |                         | $\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> $\leq$ 140 °C |     | -   | -   | 2   | А    |
| $V_R$              | reverse voltage         | T <sub>j</sub> = 25 °C   |     | -   | -   | 30  | V    |
| $V_{F}$            | forward voltage         | I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C                           |     | -   | 400 | 450 | mV   |
| I <sub>R</sub>     | reverse current         | V <sub>R</sub> = 30 V; T <sub>j</sub> = 25 °C                          |     | -   | 35  | 100 | μΑ   |

[1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.



## 5. Pinning information

#### **Table 2. Pinning information**

| Pin | Symbol | Description | Simplified outline  | Graphic symbol       |
|-----|--------|-------------|---------------------|----------------------|
| 1   | K      | cathode[1]  |                     | к- <del>][</del> - А |
| 2   | А      | anode       | 1 2 2 CFP5 (SOD128) | sym001               |

<sup>[1]</sup> The marking bar indicates the cathode.

## 6. Ordering information

### **Table 3. Ordering information**

| Type number   | Package |  |         |  |  |  |  |
|---------------|---------|--|---------|--|--|--|--|
|               | Name    | Description  | Version |  |  |  |  |
| PMEG3020BEP-Q |         | plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body | SOD128  |  |  |  |  |

## 7. Marking

#### Table 4. Marking codes

| Type number   | Marking code |
|---------------|--------------|
| PMEG3020BEP-Q | A4           |

## 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol             | Parameter                           | Conditions   |     | Min | Max  | Unit |
|--------------------|-------------------------------------|--|-----|-----|------|------|
| $V_R$              | reverse voltage                     | T <sub>j</sub> = 25 °C   |     | -   | 30   | V    |
| I <sub>F(AV)</sub> | average forward current             | $\delta$ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 100 °C    | [1] | -   | 2    | Α    |
|                    |                                     | $\delta$ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 140 °C     |     | -   | 2    | Α    |
| I <sub>FSM</sub>   | non-repetitive peak forward current | t <sub>p</sub> = 8 ms; square wave; T <sub>j(init)</sub> = 25 °C |     | -   | 50   | Α    |
| P <sub>tot</sub>   | total power dissipation             | T <sub>amb</sub> ≤ 25 °C   | [2] | -   | 625  | mW   |
|                    |                                     |  | [3] | -   | 1.05 | W    |
|                    |                                     |  | [1] | -   | 2.1  | W    |
| Tj                 | junction temperature                |  |     | -   | 150  | °C   |
| T <sub>amb</sub>   | ambient temperature                 |  |     | -55 | 150  | °C   |
| T <sub>stg</sub>   | storage temperature                 |  |     | -65 | 150  | °C   |

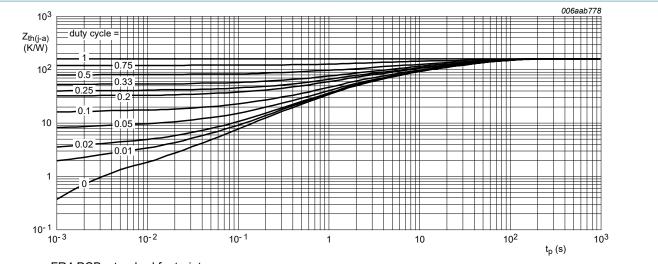
- [1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

#### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

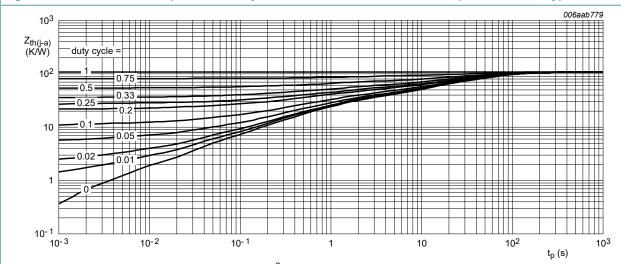
| Symbol                | Parameter  | Conditions  |         | Min | Тур | Max | Unit |
|-----------------------|--|-------------|---------|-----|-----|-----|------|
| $R_{th(j-a)}$         | thermal resistance from                          | in free air | [1] [2] | -   | -   | 200 | K/W  |
| junction to ambient   | junction to ambient                              |             | [3] [2] | -   | -   | 120 | K/W  |
|                       |  |             | [4] [2] | -   | =   | 60  | K/W  |
| R <sub>th(j-sp)</sub> | thermal resistance from junction to solder point |             | [5]     | -   | -   | 12  | K/W  |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.



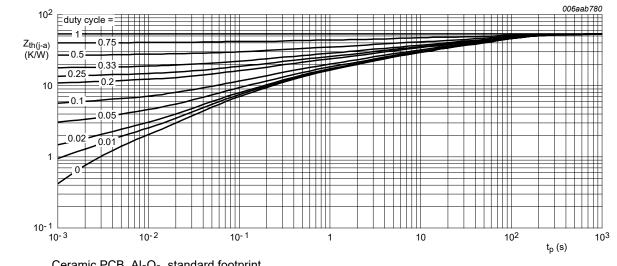
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

**Table 7. Characteristics** 

| Symbol         | Parameter         | Conditions   | Min | Тур | Max | Unit |
|----------------|-------------------|--|-----|-----|-----|------|
| V <sub>F</sub> | forward voltage   | I <sub>F</sub> = 0.1 A; T <sub>j</sub> = 25 °C           | -   | 290 | 340 | mV   |
|                |                   | I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C           | -   | 340 | 400 | mV   |
|                |                   | I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C             | -   | 365 | 420 | mV   |
|                |                   | I <sub>F</sub> = 1.5 A; T <sub>j</sub> = 25 °C           | -   | 385 | 440 | mV   |
|                |                   | I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C             | -   | 400 | 450 | mV   |
| I <sub>R</sub> | reverse current   | V <sub>R</sub> = 5 V; T <sub>j</sub> = 25 °C             | -   | 4   | -   | μΑ   |
|                |                   | V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C            | -   | 6   | -   | μΑ   |
|                |                   | V <sub>R</sub> = 30 V; T <sub>j</sub> = 25 °C            | -   | 35  | 100 | μΑ   |
| C <sub>d</sub> | diode capacitance | V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C  | -   | 340 | -   | pF   |
|                |                   | V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C | -   | 120 | -   | pF   |

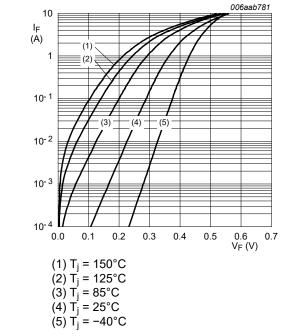
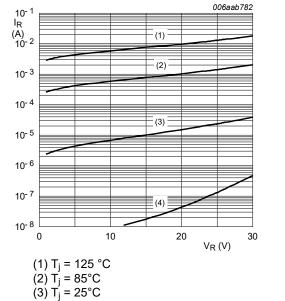


Fig. 4. Forward current as a function of forward voltage; typical values



(2)  $T_j = 85^{\circ}C$ (3)  $T_j = 25^{\circ}C$ (4)  $T_i = -40 \, ^{\circ}C$ 

Fig. 5. Reverse current as a function of reverse voltage; typical values

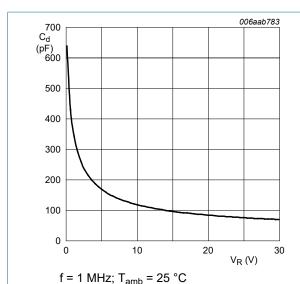
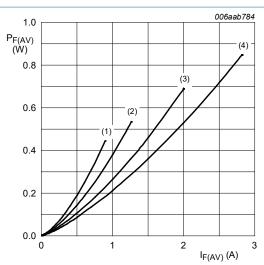
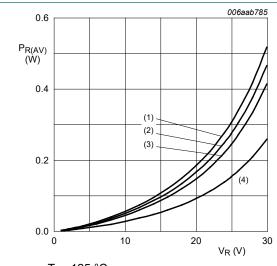


Fig. 6. Diode capacitance as a function of reverse voltage; typical values



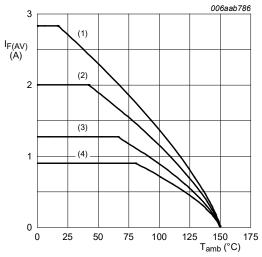
 $T_j = 150 \,^{\circ}\text{C}$ (1)  $\delta = 0.1$ (2)  $\delta = 0.2$ (3)  $\delta = 0.5$ (4)  $\delta = 1$ 

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 125 \,^{\circ}\text{C}$ (1)  $\delta = 1$ (2)  $\delta = 0.9$ (3)  $\delta = 0.8$ (4)  $\delta = 0.5$ 

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint T<sub>i</sub> = 150 °C

 $(1) \delta = 1$ ; DC

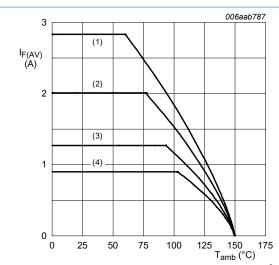
(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values

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FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_i = 150 \, ^{\circ}C$ 

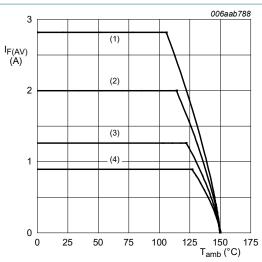
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

T<sub>i</sub> = 150 °C

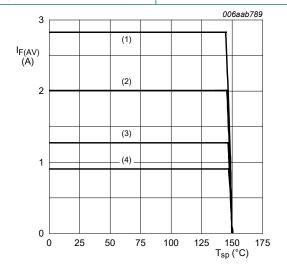
(1) δ = 1; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



T<sub>i</sub> = 150 °C

 $(1) \delta = 1; DC$ 

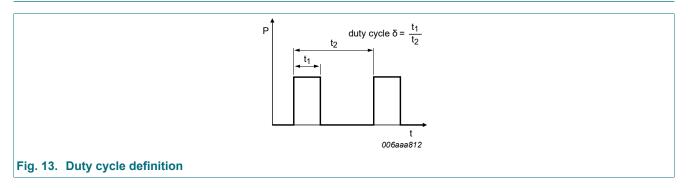
(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

## 11. Test information

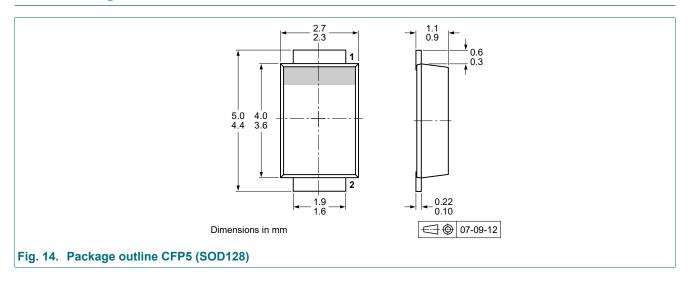


The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

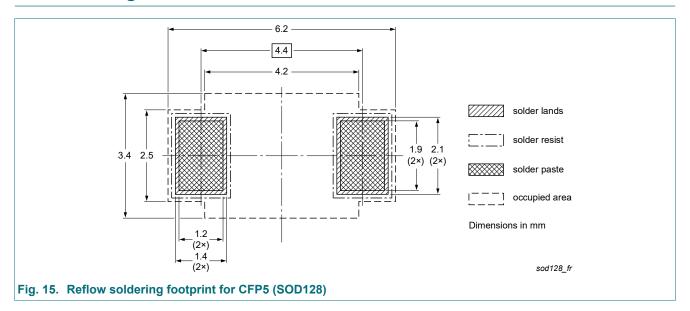
#### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

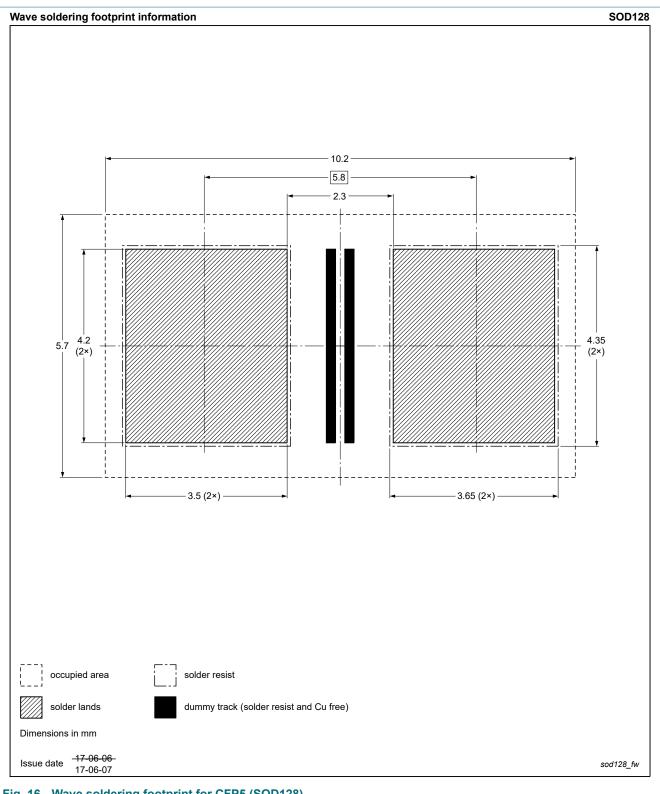
# 12. Package outline



## 13. Soldering



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# 14. Revision history

#### **Table 8. Revision history**

| Data sheet ID     | Release date | Data sheet status  | Change notice | Supersedes |
|-------------------|--------------|--------------------|---------------|------------|
| PMEG3020BEP-Q v.1 | 20210608     | Product data sheet | -             | -          |

### 15. Legal information

#### **Data sheet status**

| Document status [1][2]         | Product<br>status [3] | Definition  |
|--------------------------------|-----------------------|---|
| Objective [short] data sheet   | Development           | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification         | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production            | This document contains the product specification.                                     |

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Date of release: 8 June 2021

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